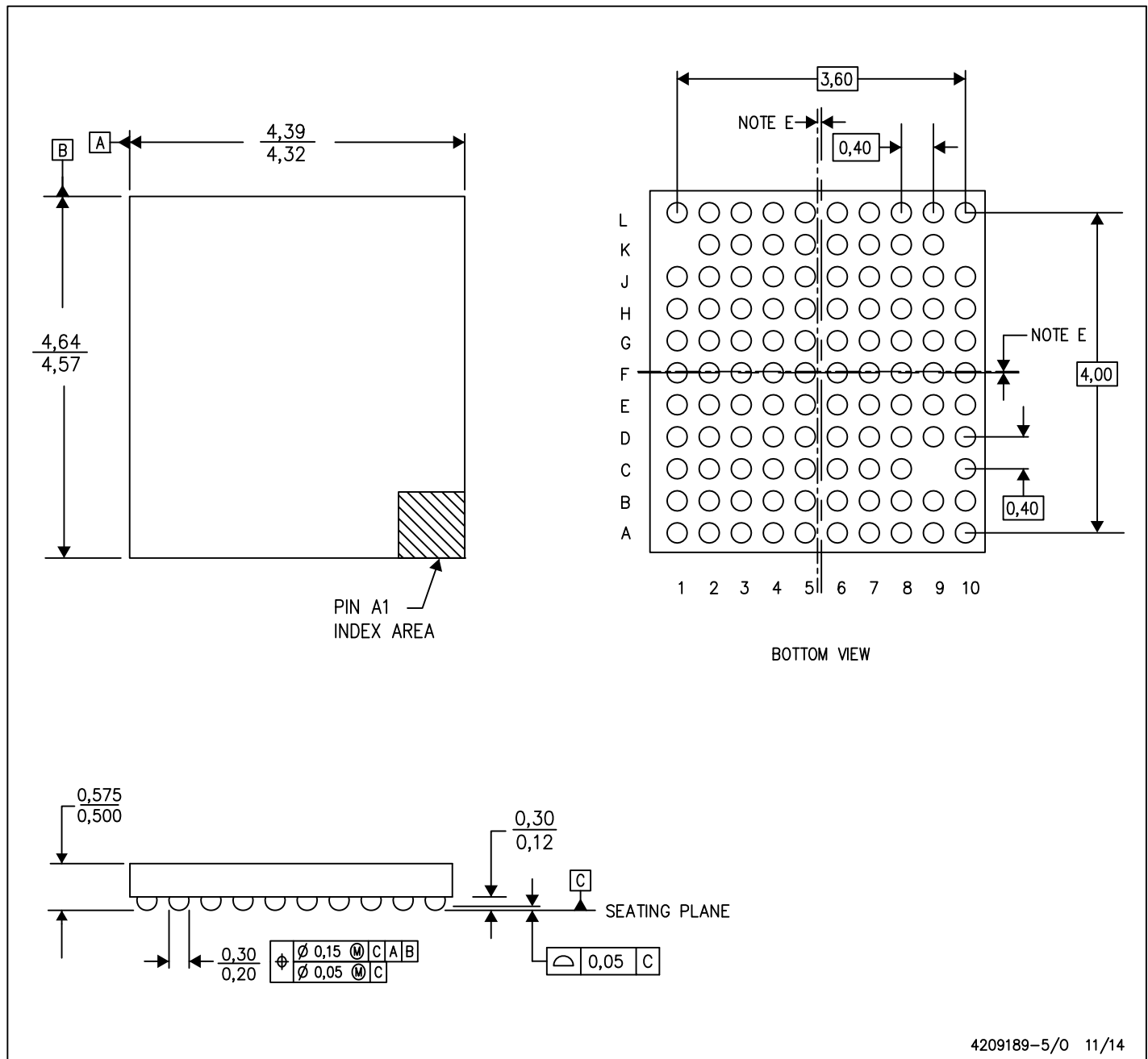


YFV (R-XBGA-N107)

DIE-SIZE BALL GRID ARRAY (WCSP)



4209189-5/0 11/14

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.
 - D. This package contains Pb-free balls.
 - E. Center of ball array offset from center of die X= + 76 μm , Y= - 13 μm .

NanoFree is a trademark of Texas Instruments.

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